



Materials Processing Announcement

Soshu Kirihara

Osaka University, Japan

Meetings International presents the Laser Materials Processing Conference, scheduled on May 20-21, 2021 at Osaka, Japan which will allow the professional to characteristic their exploration of work through introductions and have a probability to select up mastering about the present circumstance of Materials Engineering. Major attractions of this event would revolve around keynote presentations, oral presentations and poster presentations. This year we are focusing on the theme "Estimating the future laser marketing".

Laser Materials Processing seems to be the constantly trending subject matter with modern day research technologies. Everyone who explores to strengthen their knowledge and gain

extended about advanced technical cleverness is welcome to present/get new ideas. Materials Processing Conference captivates individuals both from commercial and academic worlds yet establishes a firm link and binds us together with the recent updated accomplishments. We provide a good opportunity by admiring your updated research and also by publishing it in our respective journals. We assure our attendees return to their place with the self-belief to improve their abilities and outfitted with certified approaches to work with us. This meeting will allow the attendees to acquire these new updates and share their experiences with well-recognized speakers globally.